Power Inductor

BDCC Series





Overview

The BDCC series is the special design to enhance the performance of PFM and PWM applications. It provides lower Rac value at light load and lower Rdc value at heavy load to improve efficiency performance. Furthermore, it provides excellent saturation current to reduce the ripple current and enhance efficiency.

Benefits

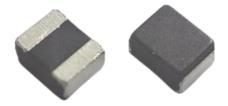
- 1. Chip Size: 2012mm; Low profile: 0.8mm
- 2. Low Rdc for better power efficiency management
- 3. High saturation curren
- 4. L Type Termination

Applications

- 1. DC-DC buck converter for power management
- 2. 5G, Cell phone

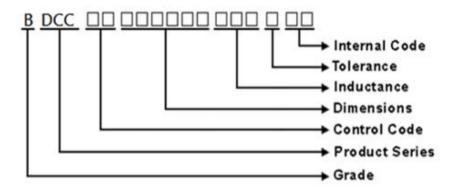
Product Information

Series	L <u>(mm)</u>	W <u>(mm)</u>	T <u>(mm)</u>	Inductance (μH)
BDCC	2	1.25	8.0	0.24, 0.33, 0.47





- 1 Scope: This specification applies to Molding power inductors
- 2 Part Numbering:



3 Rating:

Operating Temperature: - 40°C ~125°C(Including self-temperature rise)

4 Marking:

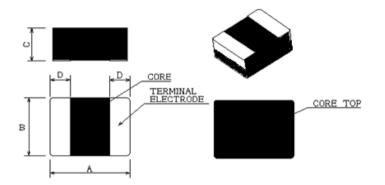
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°ℂ)	20 to 30°C
Humidity	Ordinary Humidity(25 to 85% RH)	50 to 80 %RH



6 Configuration and Dimensions:



Dimensions in mm

TYPE	201208
А	2.0±0.2
В	1.25±0.2
С	0.8 Max.
D	0.6±0.3

Net Weight (grms)

S	Size Code	Net Weight (grms)
	201208	≒0.0136

7 Electrical Characteristics:

Part No.	Inductance (uH)	Tolerance (±%)	Test Freq.	Irms(A) Max.(Typ)	Isat(A) Max.(Typ)	RDC(mΩ) Max.(Typ)	
BDCC00201208R24MWA	0.24	20	2MHZ,1V	4.2(4.3)	5.5(6.0)	22(18)	
BDCC00201208R33MWA	0.33	20	2MHZ,1V	4.0(4.2)	4.8(5.8)	24(20)	
BDCC00201208R47MWA	0.47	20	2MHZ,1V	3.7(3.9)	4.3(4.8)	29(25)	

NOTE:

6. Rated current: Isat or Irms, whichever is smaller

^{1.} Operating temperature range - 4 0 $^{\circ}$ C ~ 1 2 5 $^{\circ}$ C(Including self - temperature rise)

^{2.}Isat for Inductance drop 30% from its value without current.

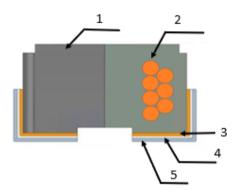
^{3.}Irms for a 40°C temperature rise from 25°C ambient.

^{4.}All test data is referenced to 25°C ambient

^{5.} Absolute maximum voltage 20VDC



- 8 BDCC00201208 Series
 - 8.1 Construction:



8.2 Material List:

Item	Part	Description	
1	Core	Metal Powder	
2	Wire	Copper wire	
3		Cu	
4	Terminal	Ni	
5		Sn	



BDCC00201208 Series Specification 9 Reliability Of Molding power inductors

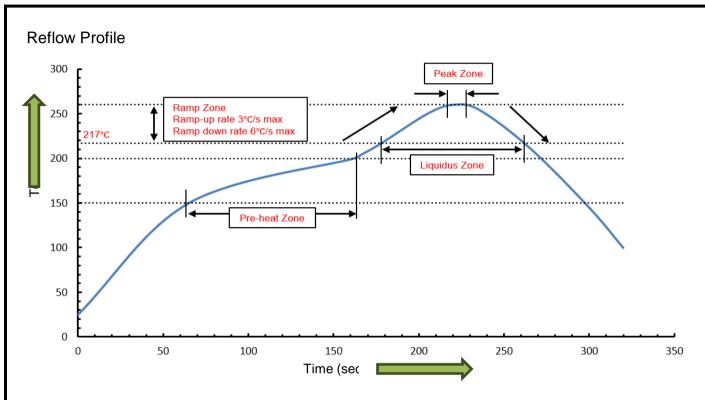
1-1.Mechanical Performance

No	ltem	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		metal body	Keeping Time: 30sec
1-1-2	Vibration	Appearance:No damage (for	Test device shall be soldered on the substrate
		microscope of CASTOR MZ-45 20X)	Oscillation Frequency: 10 to 55 to 10Hz for 1min
		Inductance change shall be	Amplitude: 1.5mm
		within ±20%	Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the terminal.	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°C
		with solder.	Immersion Time: 10±1sec
		Inductance: within ±20% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°ℂ
			Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate,
		Chip	then apply a force in the direction of the arrow.
		¶ IIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIIII	Force : 5N
			Keeping Time: 10±1sec
		Mounting Pad	

1-2 Environmental Performance

1-2.Environmental Performance							
No	ltem	Specification		Test Method			
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:				
		Inductance:within±20% of	Step	Temperature (°ℂ)	Time (min)		
		initial value	1	-40±3	30		
			2	25±2	3		
			3	125±3	30		
			4	25±2	3		
			Total: 100	cycles			
			Measured	after exposure in the room cond	dition for 24hrs		
1-2-2	Humidity Resistance		Temperatu	ıre: 60±2°ℂ			
			Relative H	umidity: 90 ~ 95% / Time: 1000l	hrs		
			Measured	after exposure in the room cond	dition for 24hrs		
1-2-3	High		Temperatu	ıre: 125±3℃			
	Temperature Resistance		Relative H	umidity: 0% / Time: 1000hrs			
			Measured	after exposure in the room cond	dition for 24hrs		
1-2-4	Low		Temperatu	ıre: -40±3°ℂ			
	Temperature Resistance		Relative Humidity: 0% / Time: 1000hrs				
			Measured	after exposure in the room cond	dition for 24hrs		





Refer to J-STD-020F

Profile Feature	Pre-heat Zone	Ramp-up Zone	Liquidus Zone	Peak Zone	Ramp-down Zone
Temperature	150~200°C	217°C~Tp	above 217°C	above 255°C	Tp~217°C
Time	60~120sec		60~150sec	<30sec	
Rate		< 3°C/sec			< 6°C/sec

Note:

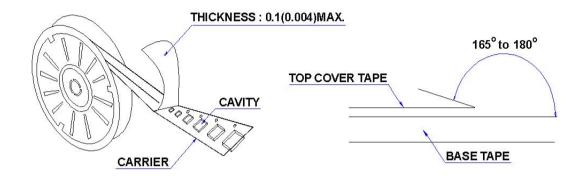
- 1. Tp<260°C
- 2. Time [25°C to peak temperature] < 8 minutes
- 3. Reflow soldering must not be performed more than 3 times.
- 4. For superior solder joint connectivity results, soldering under standard nitrogen atmosphere is recommended.



10 Packaging:

10.1 Packaging -Cover Tape

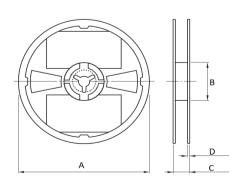
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



10.2 Packaging Quantity

TYPE	PCS/REEL
201208	3000

10.3 Reel Dimensions



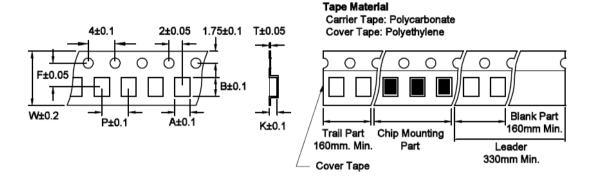
Dimensions in mm

TYPE	Α	В	С	D		
201208	178	60	12	1.5		



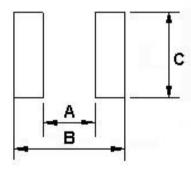
10 Packaging:

10.4 Tape Dimensions in mm



TYPE	А	В	Т	W	Р	F	K
201208	1.48	2.27	0.22	8	4	3.5	1.10

11 Recommended Land Pattern:



Dimensions in mm

TYPE	Α	В	С
201208	8.0	2.4	1.45

12 Note:

- 1. The storage period is within 12 months. Products should be stored in the warehouse on the following condition: (Temperature: 5~40°C; Humidity: 20%~75%RH). Solderability should be checked if the period is exceeded.
- 2. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 3. Do not knock nor drop.
- 4. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 5. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)



